

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1) and classification adj defects and specific adj process and number adj defects and photos and illumination	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 13:17
L2	0	L1 and (first and second)adj wafer	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 13:26
L3	0	L1 and (first and second)adj wafer and defect\$3	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 13:26
S1	571947	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:27
S2	1	S1 and automatic and defect adj classification and teaching and knowledge adj based adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:29
S3	1	automatic and defect adj classification and teaching and knowledge adj based adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:30
S4	1	S1 and defect adj classification and teaching and knowledge adj based adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:30

S5	1	defect adj classification and teaching and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:30
S6	2	defect adj classification and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:31
S7	82	defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:31
S8	19	S7 and (water\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:31
S9	17	S8 and(@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @ptad<"20030712")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:36
S10	12	S8 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:36
S11	24	((DIRK) near2 (SOENKSEN)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:36
S12	11	((RALF) near2 (FRIEDRICH)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:37
S13	1	((ANDREAS) near2 (DRAEGER)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:37
S14	2	((DETLEF) near2 (SCHUPP)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:37
S16	2	((THIN) near2 ("VAN LUU")).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:39
S17	3	((WOLFGANG) near2 (LANGER)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:39

S18	0	S11 and defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:40
S19	0	S11 and defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:40
S20	0	S11 and defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:41
S21	0	S12 and defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:41
S22	0	S13 and defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:43
S23	3	S10 and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:46
S24	638382	S23 and select\$3 and review and data file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:47
S25	0	S23 and select\$3 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:47
S26	18	S7 and select\$3 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:48

S27	0	S26 and parameters and learning adj node	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:49
S28	0	S26 and parameters and learning adj mode	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:49
S29	17	S26 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:49
S30	2	S1 and S7 and S24 and S29	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:56
S31	2	S30 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:56
S32	18	S7 and S26	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:57
S33	16	S32 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:58
S34	20	S1 and automatic and defect adj recognition	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:00
S35	638382	S34 and select\$3 and review and data file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:01

S36	4	S34 and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:33
S37	1	S34 and learning adj mode	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:34
S38	0	S37 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:34
S39	16	S34 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:35
S40	0	S39 and learning adj mode	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:35
S41	2	S39 and learning	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:35
S42	16	S26 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:39
S43	0	S42 and learning adj mode	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:40
S44	0	S42 and learning near mode	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:40

S45	0	S42 and learning near3 mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:40
S46	11	S42 and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:40
S47	598	S1 and select\$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:44
S48	340	S47 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:44
S49	1	S48 and input and user and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:45
S50	1	S48 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:46
S51	4	S48 and alignment adj procedure	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:46
S52	0	S8 and automatic adj defect and recognition and(detect\$3 or determining)same (defect or flaw or fault)same(assign\$3 or test\$3 or evaluat\$3)same descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:02
S53	0	S48 and automatic adj defect and recognition and(detect\$3 or determining)same (defect or flaw or fault)same(assign\$3 or test\$3 or evaluat\$3)same descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:02

S54	1	automatic adj defect and recognition and(detect\$3 or determining)same (defect or flaw or fault)same(assign\$3 or test\$3 or evaluat\$3)same descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:02
S55	11	automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:03
S56	5	S55 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:03
S57	1	S56 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:03
S58	0	S57 and edit adj recipe	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:05
S59	0	S57 and edit	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:05
S60	0	S57 and memory adj circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:07
S61	1	S57 and circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:07
S62	0	S61 and logic adj circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 13:08

S63	0	S61 and blank adj wafer\$1	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:08
S64	1	S66 and learning adj mode	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 14:02
S65	571947	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:12
S66	2	S65 and select\$3 and review adj data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:13
S67	2	S65 and review adj data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:13
S68	638	S65 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:14
S69	134	S65 and review same data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:14
S70	0	S69 and defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
S71	0	S69 and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15

S72	1	S69 and classification and knowledge near3 database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
S73	11	S68 and classification and knowledge near3 database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
S74	5	S73 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:16
S75	5	S74 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:16
S76	1	S75 and (user or operator or human) and page and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:17
S77	1	S75 and (user or operator or human) and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:17
S78	9	S68 and (detect\$3 or determining) and (defect or fault or flaw) and classification and knowledge near3 database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:19
S79	13	learning and (knowledge-based or knowledge adj based) and database and automatic and defect adj classification	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:21
S80	10	S79 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:21

S81	0	S80 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:21
S82	1	S80 and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:22
S83	8	S80 and (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:24
S84	8	S83 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:24
S85	6	S84 and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:43
S86	5	S84 and descriptor adj (defect or fault or flaw)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:46
S87	573639	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:04
S88	19	S87 and defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:05
S89	640949	S88 and select\$3 and review and data file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:05

S90	2	S88 and select\$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:05
S91	8	S87 and display adj thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:07
S92	2	S91 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:07
S93	0	S92 and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:15
S94	8	S91 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:27
S95	1	S94 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:29
S96	2	S92 and display adj thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:30
S97	2	S96 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:30
S98	0	S97 and circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:31

S99	0	S97 and defect and (classification or classifier or classify)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:32
S100	0	S97 and(classification or classifier or classify or grouping)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:33
S101	0	S97 and intensity	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:33
S102	2	S97 and (intensity or contrast or brightness)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:34
S103	2	S102 and(illumination or source or light)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:34
S104	2	S103 and(blank adj wafer\$1 or wafer\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:36
S105	2	S104 and(polymer or layer or oxide adj layer or contact or metal)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:38
S106	0	S105 and lens	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:39
S107	0	S105 and focus	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:39

S108	0	S105 and magnificat\$3	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:40
S109	2	S105 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:40
S110	2	S109 and select\$3 adj recipe	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/17 19:41
S111	2	"6973209".pn.	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:40
S112	0	S111 and alignment	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:40
S113	1	S111 and align\$3	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:40
S114	0	S111 and align\$3 same light	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:41
S115	1	S111 and align\$3 and(light or source or illuminat\$3)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:41
S116	1	S115 and adjusting	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:42

S117	0	S116 and optimal adj intensity	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:42
S118	1	S116 and optimal	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:42
S119	0	S118 and intensity	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:42
S120	1	S118 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:43
S121	1	S120 and algorithm	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:46
S122	1	S121 and automatic	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:47
S123	0	S122 and intensity	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:47
S124	1	S122 and (intensity or contrast or brightness)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:47
S125	0	S124 and text adj image\$1	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 15:48

S126	0	S124 and text	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:48
S127	1	S124 and recipe	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:49
S128	0	S127 and review	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:49
S129	1	S127 and dictionary	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:49
S130	1	S129 and registered	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:50
S131	1	S130 and drag	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:51
S132	82	defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:09
S133	18	S132 and select\$3 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:09
S134	16	S133 and @ad< "20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:09

S135	0	S132 and select\$3 same review adj data	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 16:13
S136	5	S132 and review adj data	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 16:13
S137	3	S136 and @ack<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 16:14
S138	1	S137 and descriptors	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 16:19
S139	0	S137 and defect adj descriptors	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/19 16:20
S140	82	defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/30 11:44
S141	5	S140 and review adj data	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/30 11:44
S142	3	S141 and @ack<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/30 11:44
S143	2	S142 and(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/30 11:45

SI44	3	"6408219".pn.	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:46
SI45	1	SI44 and review adj data	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:47
SI46	1	SI44 and select\$3	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:48
SI47	732	select\$3 same review adj data	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50
SI48	62	SI47 and(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50
SI49	0	SI48 and defect and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50
SI50	0	SI48 and classification and knowledge adj database	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50
SI51	14	SI48 and @ad< "20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:51
SI52	0	SI51 and display adj thumbnails	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:51

SI53	0	SI51 and display and thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:52
SI54	0	SI51 and thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:52
SI55	0	SI51 and automatic and defect adj recognition	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:12
SI56	0	SI51 and select\$3 adj recipe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:13
SI57	1	SI51 and align\$3 and(light or source or illuminat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:13
SI58	0	SI57 and(user or operator or human)and page and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:16
SI59	0	SI57 and descriptors	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:16
SI60	0	SI57 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:36
SI61	11	automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58

SI62	5	SI61 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 15:58
SI63	1	SI62 and learning adj mode	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 15:58
SI64	0	SI63 and memory adj circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 15:58
SI65	575216	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 15:58
SI66	10	SI65 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 15:59
SI67	643423	SI66 and select\$3 and review and data file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 15:59
SI68	1	SI66 and select\$3 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:00
SI69	0	SI68 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:00
SI70	1	SI66 and memory adj circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:00

SI71	0	SI70 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:01
SI72	4	SI66 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:01
SI73	0	SI72 and memory adj circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:01
SI74	7745	SI65 and memory adj circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:01
SI75	2341	SI74 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:01
SI76	775	SI75 and logic adj circuits	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:02
SI77	9	SI76 and blank adj wafer	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:02
SI78	8	SI77 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:03
SI79	0	SI78 and resist	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:03

SI80	0	SI78 and photo adj resist	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:03
SI81	0	SI78 and polymer adj layer	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:04
SI82	51765	polymer adj layer	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:04
SI83	33269	SI82 and @ack<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:04
SI84	2388	SI83 and oxide adj layer	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:05
SI85	1703	SI84 and contact	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:05
SI86	16332	SI83 and contact	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:05
SI87	10	SI86 and metal adj later	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:06
SI88	1	SI87 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:06

SI89	1	SI88 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:06
SI90	1	SI89 and(intensity or contrast or brightness)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:07
SI91	0	SI90 and align\$3 and(light or source or illuminat\$3)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:07
SI92	1	SI90 and(light or source or illuminat\$3)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:07
SI93	0	SI92 and magnificat\$3	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:08
SI94	0	SI92 and lens	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:08
SI95	0	SI92 and histogram	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:08
SI96	0	SI95 and focus\$3	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/31 16:12
SI97	51832	polymer adj layer	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:04

S198	33269	S197 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:04
S199	16332	S198 and contact	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:04
S200	10	S199 and metal adj later	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:04
S201	1	S200 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:04
S202	1	S201 and @ad<"20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:04
S203	1	S202 and(intensity or contrast or brightness)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:04
S204	1	S203 and(light or source or illuminat\$3)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:04
S205	0	S204 and metal adj layer	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:05
S206	1	S204 and metal	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/01/02 14:06

S207	0	S206 and bright adj field	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:07
S208	0	S206 and bright	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:07
S209	1	S206 and (UV or DUV)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:08
S210	0	S209 and lens	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:08
S211	0	S209 and intensity	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:09
S212	1	S209 and contrast	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:10
S213	0	S212 and histogram	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:10
S214	795256	select\$3 and review and data file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:12
S215	2665	S214 and polymer adj layer	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13

S216	12	S215 and bright adj field	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13
S217	9	S216 and (UV or DUV)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13
S218	3	S217 and @ad< "20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13
S219	3	S218 and intensity	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13
S220	0	S219 and histogram	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:14
S221	0	S219 and metal adj layer	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:14
S222	0	S219 and lens	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:14
S223	4	S216 and lens	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:15
S224	0	S223 and @ad< "20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:15

S225	0	S223 and @ad< "20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:15
S226	5025	382/149,145,224,159,100,141,155,181.CCLS.	USPAT	OR	ON	2009/06/29 11:58
S227	4478	715/774,835,837,764,841,210,839,762,809,804,973,250,866,708.CCLS.	USPAT	OR	ON	2009/06/29 12:01
S228	1453	719/310,315.CCLS.	USPAT	OR	ON	2009/06/29 12:01
S229	355	714/E11.21.CCLS.	USPAT	OR	ON	2009/06/29 12:02
S230	1846	356/237.1,237.2.CCLS.	USPAT	OR	ON	2009/06/29 12:03
S231	834	702/35,1,33.CCLS.	USPAT	OR	ON	2009/06/29 12:04
S232	599018	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:29
S233	125	S232 and user adj select\$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:32
S234	3	S233 and input adj user and page and learning adj mode and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:34
S235	4	S233 and input and user and page and learning adj mode and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:37
S236	4	S233 and learning adj mode and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:55

S237	1	S233 and automatic adj defect and recognition and (detect\$3 or determining) and (defect or flaw or fault) and (assign\$3 or test\$3 or evaluat\$3) and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:58
S238	11	automatic adj defect and recognition and (detect\$3 or determining) and (defect or flaw or fault) and (assign\$3 or test\$3 or evaluat\$3) and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:59
S239	10	S238 and (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:59
S240	1	S239 and user adj select\$3 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:00
S241	1	S239 and user adj select\$3 and review adj data	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:00
S242	3	automatic adj defect and recognition and (detect\$3 or determining) and (defect or flaw or fault) and (assign\$3 or test\$3 or evaluat\$3 or accept\$3) and select\$3 adj (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1) and (capturing or pictures or cod or camera) and (illumination or source or light or optimal adj intensity or light adj intensity)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:12
S243	3	automatic adj defect and recognition and (detect\$3 or determining) and (defect or flaw or fault) and (assign\$3 or test\$3 or evaluat\$3 or accept\$3) and select\$3 adj (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1) and (capturing or pictures or cod or camera) and align\$4 and (illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:16
S244	0	S243 and (@ad<"20030712" or @rad<"20030712" or @prad<"20030712" or @ptad<"20030712")	US-PGRUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:17
S246	781	S226 and (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	USPAT	OR	ON	2009/06/29 13:19
S247	3	S246 and user adj select\$3 and review and data adj file	USPAT	OR	ON	2009/06/29 13:19

S248	27	S246 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:20
S249	0	S248 and input and user and page and learning adj mode and parameters	USPAT	OR	ON	2009/06/29 13:21
S251	0	S248 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or ccd or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:23
S252	0	S248 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or ccd or camera)and (illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:24
S253	2	S248 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 13:25
S254	2	S253 and(@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @ptad<"20030712")	USPAT	OR	ON	2009/06/29 13:28
S255	0	S253 and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or ccd or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:32
S256	0	S253 and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or ccd or camera)and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:43
S257	0	S253 and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or ccd or camera)and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)and(detected\$3 or determining)and(defect or flaw or fault)	USPAT	OR	ON	2009/06/29 13:46
S258	18	S227 and(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	USPAT	OR	ON	2009/06/29 13:48
S259	4	S258 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:48
S260	0	S259 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 13:48
S261	0	S259 and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or ccd or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:52
S262	2	S228 and(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	USPAT	OR	ON	2009/06/29 13:53
S263	0	S262 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 13:55

S264	0	S262 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:56
S265	0	S262 and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:56
S266	2	S228 and(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	USPAT	OR	ON	2009/06/29 13:59
S267	1	S229 and(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	USPAT	OR	ON	2009/06/29 13:59
S268	0	S267 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 13:59
S269	0	S267 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:59
S270	0	S267 and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:00
S271	733	S230 and(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	USPAT	OR	ON	2009/06/29 14:01
S272	5	S271 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 14:01
S273	0	S272 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:01
S274	0	S272 and select\$3 adj(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:01
S275	5	S272 and(@ad<"20030712" or @rad<"20030712" or @prad<"20030712" or @ptad<"20030712")	USPAT	OR	ON	2009/06/29 14:02
S276	0	S272 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:03
S277	599018	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
S278	83	defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04

S279	19	S278 and (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
S280	12	S279 and @ad< "20030712"	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
S281	3	S280 and descriptor	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
S282	685554	S281 and select\$3 and review and data file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
S283	18	S278 and select\$3 and review and data adj file	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
S284	17	S283 and parameters	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
S285	2	S277 and S278 and S282 and S284	US-PGRUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2009/06/29 14:04
S286	0	S285 and @ad< "20030712"	USPAT	OR	ON	2009/06/29 14:04
S288	129	S231 and (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	USPAT	OR	ON	2009/06/29 14:06
S289	4	S288 and user adj select\$3 and review and (storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:06
S290	0	S289 and select\$3 adj (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1) and (capturing or pictures or cod or camera) and align\$4 and (illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:07

S291	0	S289 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 14:08
S292	3	S289 and(@adk~"20030712" or @adac~"20030712" or @prad~"20030712" or @ptad~"20030712")	USPAT	OR	ON	2009/06/29 14:09
S293	0	S292 and select\$3 adj(water\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:23
S294	1	S288 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 14:26
S295	0	S294 and select\$3 adj(water\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:26
S296	0	S294 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:28
S304	1	((water\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and user adj select\$3 and review and data adj file and input and user and page and learning adj mode).dm.	US-PGPUB	OR	ON	2009/06/29 14:51
S306	1	S294 and automatic adj defect and recognition and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 14:55
S307	0	S306 and select\$3 adj(water\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:59
S308	0	S306 and select\$3 adj(water\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:59
S309	0	accept\$3 adj select\$3 adj(water\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 15:14
S310	0	accept\$3 adj select\$3 adj(water\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 15:15
S311	0	accept\$3 adj select\$3 adj(water\$1 or semiconductor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and(detected\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)and threshold\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 15:17

S312	599764	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGÜB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:24
S313	5	S312 and (automatic adj defect adj classification or ADC)and knowledge adj based adj database	US-PGÜB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:25
S316	0	S312 and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)same select\$3 adj number same (defect or flaw or fault)same(plurality or plural\$1 or location or first adj wafer or wafer\$1) same(capaturing or obtaining or generating or pictures or thumbnails adj image\$1 or display \$3)same(intensity or contrast or brightness or focus or out adj focus or illumination or source or light or optimal adj illuminat\$3)	US-PGÜB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:41
S317	3	S313 and(@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @ptad<"20030712")	US-PGÜB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:43
S318	0	S313 and @ad<"20030712"	US-PGÜB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:43
S319	0	S313 and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)same select\$3 adj number same (defect or flaw or fault)same(plurality or plural\$1 or location or first adj wafer or wafer\$1) same(capaturing or obtaining or generating or pictures or thumbnails adj image\$1 or display \$3)same(intensity or contrast or brightness or focus or out adj focus or illumination or source or light or optimal adj illuminat\$3)and threshold same descriptors	US-PGÜB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:46
S320	11250	S313 and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)and select\$3 adj number and(defect or flaw or fault)and(plurality or plural\$1 or location or first adj wafer or wafer\$1)and (capaturing or obtaining or generating or pictures or thumbnails adj image\$1 or display\$3) and(intensity or contrast or brightness or focus or out adj focus or illumination or source or light or optimal adj illuminat\$3)and threshold\$3 and descriptors	US-PGÜB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:47
S321	712	S320 and(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1)	US-PGÜB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:47
S322	1	S321 and (automatic adj defect adj classification or ADC)and knowledge adj based adj database	US-PGÜB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:48

S325	47	(wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1) and (assign\$3 or test\$3 or evaluat\$3 or accept\$3) and select\$3 adj number and (defect or flaw or fault) and (plurality or plural\$1 or location or first adj wafer or wafer\$1) and (capturing or obtaining or generating or pictures or thumbnails adj image\$1 or display\$3) and (intensity or contrast or brightness or focus or out adj focus or illumination or source or light or optimal adj illuminat\$3) and threshold\$3 and descriptors	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:52
S326	0	S325 and (automatic adj defect adj classification or ADC) and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:53
S327	45	S325 and (@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @ptad<"20030712")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:53
S328	4	S325 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:53
S329	7	S312 and (assign\$3 or test\$3 or evaluat\$3 or accept\$3) same select\$3 adj number same (defect or flaw or fault) same (plurality or plural\$1 or location or first adj wafer or wafer\$1) same (capturing or obtaining or generating or pictures or thumbnails adj image\$1 or display\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:57
S330	0	S329 and (@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @ptad<"20030712")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:57
S332	0	optimizat\$3 and detect\$3 adj parameters and (wafer\$1 or semiconductor\$1 or chip\$1 or substrat\$1) and (assign\$3 or test\$3 or evaluat\$3 or accept\$3) and select\$3 adj number and (defect or flaw or fault) and (plurality or plural\$1 or location or first adj wafer or wafer\$1) and (capturing or obtaining or generating or pictures or thumbnails adj image\$1 or display\$3) and (intensity or contrast or brightness or focus or out adj focus or illumination or source or light or optimal adj illuminat\$3) and threshold\$3 and descriptors	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 12:02

7/2/09 1:39:01 PM

C:\Documents and Settings\SChawan\My Documents\EAST\Workspaces\4454.wsp